

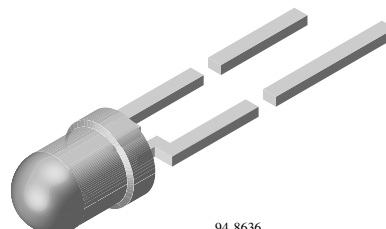
## Infrared Emitting Diode, 950 nm, GaAs

### Description

TSUS4400 is an infrared emitting diode in standard GaAs on GaAs technology, molded in a clear, blue tinted plastic package. The device is spectrally matched to silicon photodetectors.

### Features

- Low forward voltage
- High radiant power and radiant intensity
- Suitable for DC and high pulse current operation
- Standard T-1(Ø 3 mm) package
- Angle of half intensity  $\phi = \pm 18^\circ$
- Peak wavelength  $\lambda_p = 950 \text{ nm}$
- High reliability
- Good spectral matching to Si photodetectors
- Lead (Pb)-free component
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



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### Applications

- Infrared remote control systems with small package and low cost requirements in combination with silicon photo detectors. Infrared source in reflective sensors, tape end detection.

### Absolute Maximum Ratings

$T_{amb} = 25^\circ\text{C}$ , unless otherwise specified

| Parameter                           | Test condition                          | Symbol     | Value         | Unit             |
|-------------------------------------|---|------------|---------------|------------------|
| Reverse voltage                     |   | $V_R$      | 5             | V                |
| Forward current                     |   | $I_F$      | 100           | mA               |
| Peak forward current                | $t_p/T = 0.5$ , $t_p = 100 \mu\text{s}$ | $I_{FM}$   | 200           | mA               |
| Surge forward current               | $t_p = 100 \mu\text{s}$                 | $I_{FSM}$  | 2             | A                |
| Power dissipation                   |   | $P_V$      | 170           | mW               |
| Junction temperature                |   | $T_j$      | 100           | $^\circ\text{C}$ |
| Operating temperature range         |   | $T_{amb}$  | - 55 to + 100 | $^\circ\text{C}$ |
| Storage temperature range           |   | $T_{stg}$  | - 55 to + 100 | $^\circ\text{C}$ |
| Soldering temperature               | $t \leq 5 \text{ sec}$ , 2 mm from case | $T_{sd}$   | 260           | $^\circ\text{C}$ |
| Thermal resistance junction/ambient |   | $R_{thJA}$ | 450           | K/W              |

## Electrical Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified

| Parameter                  | Test condition  | Symbol     | Min | Typ.  | Max | Unit          |
|----------------------------|---|------------|-----|-------|-----|---------------|
| Forward voltage            | $I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$          | $V_F$      |     | 1.3   | 1.7 | V             |
|                            | $I_F = 1.5\text{ A}$ , $t_p = 100\text{ }\mu\text{s}$ | $V_F$      |     | 2.2   |     | V             |
| Temp. coefficient of $V_F$ | $I_F = 100\text{ mA}$                                 | $TK_{V_F}$ |     | - 1.3 |     | mV/K          |
| Reverse current            | $V_R = 5\text{ V}$                                    | $I_R$      |     |       | 100 | $\mu\text{A}$ |
| Breakdown voltage          | $I_R = 100\text{ }\mu\text{A}$                        | $V_{(BR)}$ | 5   | 40    |     | V             |
| Junction capacitance       | $V_R = 0\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0$     | $C_j$      |     | 30    |     | pF            |

## Optical Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified

| Parameter                        | Test condition  | Symbol           | Min | Typ.     | Max | Unit  |
|----------------------------------|---|------------------|-----|----------|-----|-------|
| Radiant intensity                | $I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$          | $I_e$            | 7   | 15       | 35  | mW/sr |
|                                  | $I_F = 1.5\text{ A}$ , $t_p = 100\text{ }\mu\text{s}$ | $I_e$            |     | 140      |     | mW/sr |
| Radiant power                    | $I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$          | $\phi_e$         |     | 20       |     | mW    |
| Temp. coefficient of $\phi_e$    | $I_F = 20\text{ mA}$                                  | $TK_{\phi_e}$    |     | - 0.8    |     | %/K   |
| Angle of half intensity          |   | $\varphi$        |     | $\pm 18$ |     | deg   |
| Peak wavelength                  | $I_F = 100\text{ mA}$                                 | $\lambda_p$      |     | 950      |     | nm    |
| Spectral bandwidth               | $I_F = 100\text{ mA}$                                 | $\Delta\lambda$  |     | 50       |     | nm    |
| Temp. coefficient of $\lambda_p$ | $I_F = 100\text{ mA}$                                 | $TK_{\lambda_p}$ |     | 0.2      |     | nm/K  |
| Rise time                        | $I_F = 100\text{ mA}$                                 | $t_r$            |     | 800      |     | ns    |
|                                  | $I_F = 1.5\text{ A}$                                  | $t_r$            |     | 400      |     | ns    |
| Fall time                        | $I_F = 100\text{ mA}$                                 | $t_f$            |     | 800      |     | ns    |
|                                  | $I_F = 1.5\text{ A}$                                  | $t_f$            |     | 400      |     | ns    |
| Virtual source diameter          |   | $\varnothing$    |     | 2.1      |     | mm    |

## Typical Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified

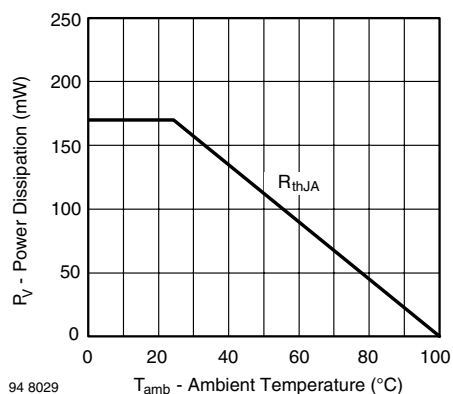


Figure 1. Power Dissipation vs. Ambient Temperature

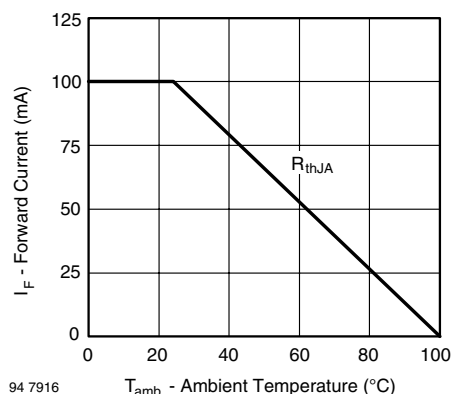


Figure 2. Forward Current vs. Ambient Temperature

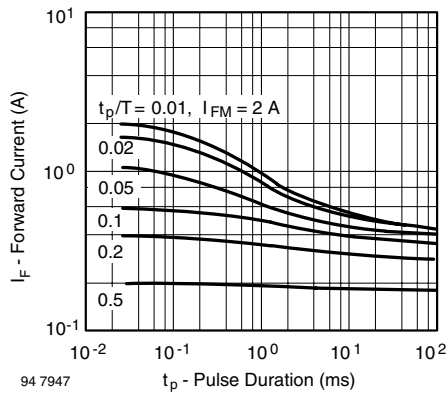


Figure 3. Pulse Forward Current vs. Pulse Duration

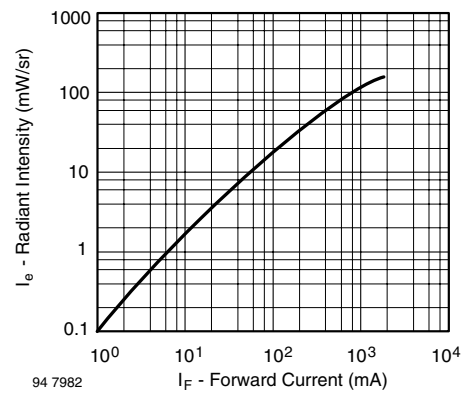


Figure 6. Radiant Intensity vs. Forward Current

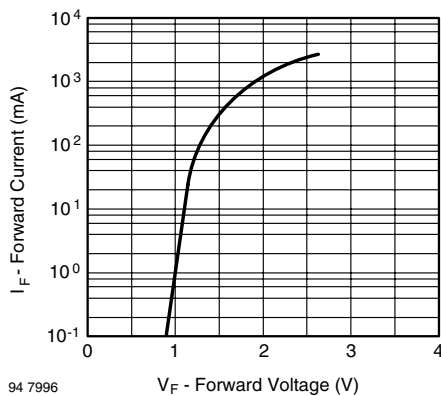


Figure 4. Forward Current vs. Forward Voltage

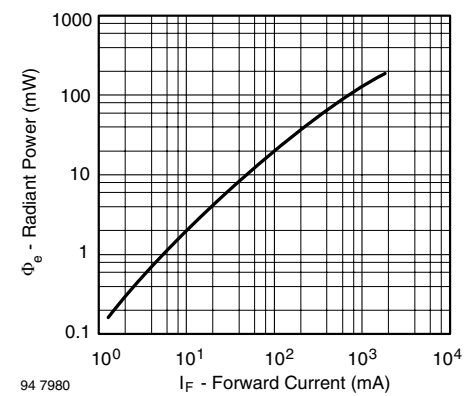


Figure 7. Radiant Power vs. Forward Current

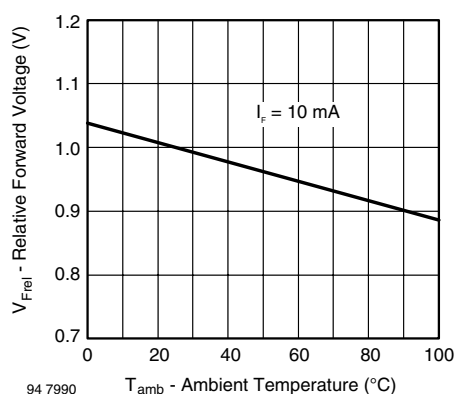


Figure 5. Relative Forward Voltage vs. Ambient Temperature

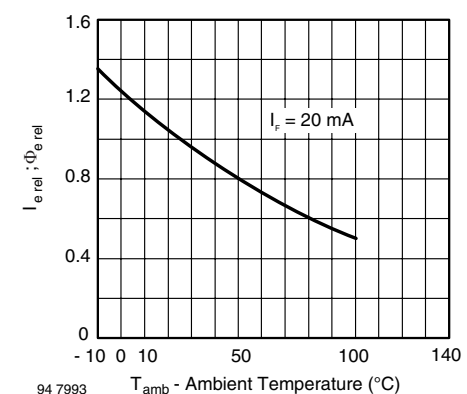


Figure 8. Rel. Radiant Intensity/Power vs. Ambient Temperature

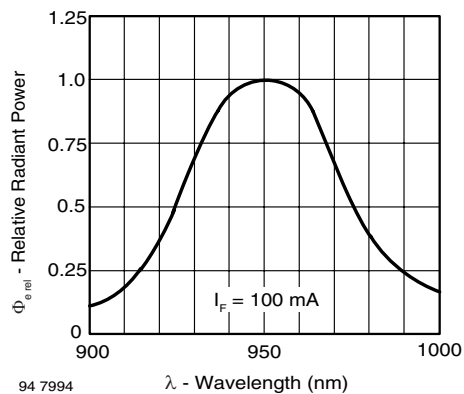


Figure 9. Relative Radiant Power vs. Wavelength

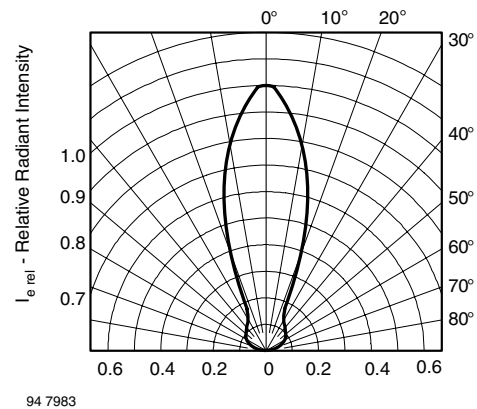
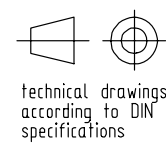
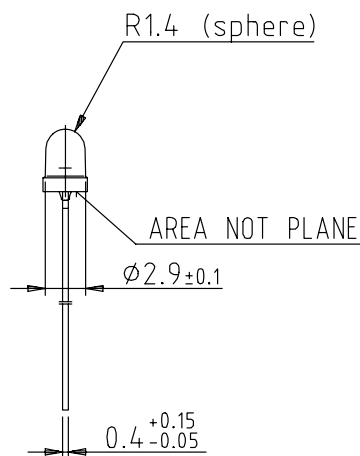
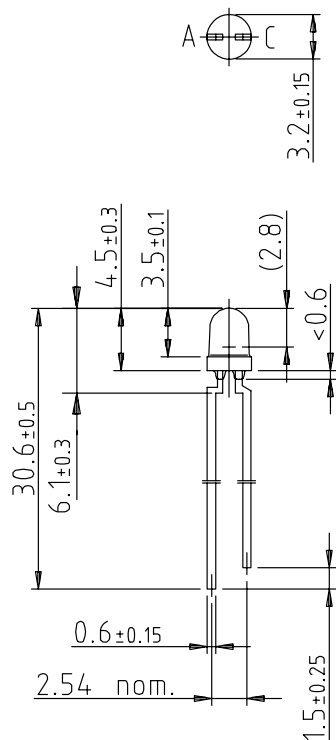


Figure 10. Relative Radiant Intensity vs. Angular Displacement

## Package Dimensions in mm



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2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

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The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

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